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Carol Redinger 4/12/06
(Signature & date)

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In the United States Patent and Trademark Office

Date: 4/12/06
In re Kevin Petrarca, et al.
Filed: 09/30/04
Application of:
For: **Homogeneous Copper Interconnects for BEOL**

Serial Number: 10/711,700
Art Unit: 2818
Confirmation No. 5699
Examiner: Paula McCray

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit the PTO-1449, attached hereto.

Each item of information contained the attached Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to filing of the attached Information Disclosure Statement.

In citing these documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that better art than that listed is not available, or that other art is not applicable.

The Commissioner is hereby authorized to charge the fee in 37 CFR 1.17(P) for submission of an Information Disclosure Statement to Deposit Account No. 09-0458.

Respectfully submitted,
Kevin Petrarca, et al.

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FIS920040258US1

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

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PATENT & TRADEMARK OFFICE

Docket Number (Optional)

FIS920040258US1

Application Number

10/711,700

Applicant(s)

Kevin Petrarca, et al.

Filing Date

09/30/04

Group Art Unit

2818

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
	AA**	US-5,484,518	01/1996	GOLDBERG	
	AB**	US-6,261,433	07/2001	LANDAU	
	AC**	US-6,331,237	12/2001	ANDRICACUS et al.	
	AD**	US-6,113,771	09-05-2000	LANDAU et al.	

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document Country Code ³ -Number ⁴ -Kind Code ⁵ (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
	BA**	EP-0952242	11-16-1998	LANDAU, et al.		

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. **CITE NO.: Those patent(s) or publication(s) which are marked with an double asterisk (**) next to the Cite No. are not supplied because they were previously cited by or submitted to the Office in a prior application relied upon in this application for an earlier filing date under 35 U.S.C. 120. ¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
	CA**	A Novel Electrolyte Composition for Copper Plating in Wafer Metallization, Electrochemical Processing in ULSI Fabrication and Semiconductor/Metal Deposition II: Proceedings of the International Symposium; P.C.: Uziel LANDAU, et al., The Electrochemical Society, Inc. Proceedings Volume 99-9.	
	CB**	A Model of Superfilling in Damascene Electroplating, H. DELIGIANI, et al.; The 195 th Meeting of Electrochemical Society, Inc. Meeting Abstracts, Volume 99-1 (May 2-6, 1999).	
	CC**	Model of Wafer Thickness Uniformity in an Electroplating Tool, The 195 th Meeting of Electrochemical Society, Inc. Meeting Abstracts, Volume 99-1 (May 2-6, 1999).	
	CD**	A Model of Superfilling in Damascene Electroplating, H. DELIGIANI, et al.; Electrochemical Processing in ULSI Fabrication and Semiconductor/Metal Deposition II: Proceedings of the International Symposium; P.C.: Uziel LANDAU, et al., The Electrochemical Society, Inc., Proceedings Volume 99-9.	
	CE**	Uziel LANDAU, A Novel Electrolyte Composition for Copper Plating in Wafer Metallization, Abstract No. 263.	
	CF**	Model of Wafer Thickness Uniformity in an Electroplating Tool, Electrochemical Processing in ULSI Fabrication and Semiconductor/Metal Deposition II: Proceedings of the International Symposium; P.C.H. DELIGIANI, et al., The Electrochemical Society, Inc., Proceedings Volume 99-9.	
	CG**	Computational Aspects of the Terminal Effect on Wafer-Scale Uniformity, H. DELIGIANI et al.; The 195 th Meeting of Electrochemical Society, Inc. Meeting Abstracts, Volume 99-1 (May 2-6, 1999).	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. **CITE NO.: Those patent(s) or publication(s) which are marked with an double asterisk (**) next to the Cite No. are not supplied because they were previously cited by or submitted to the Office in a prior application relied upon in this application for an earlier filing date under 35 U.S.C. 120.

Examiner Signature	Date Considered
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